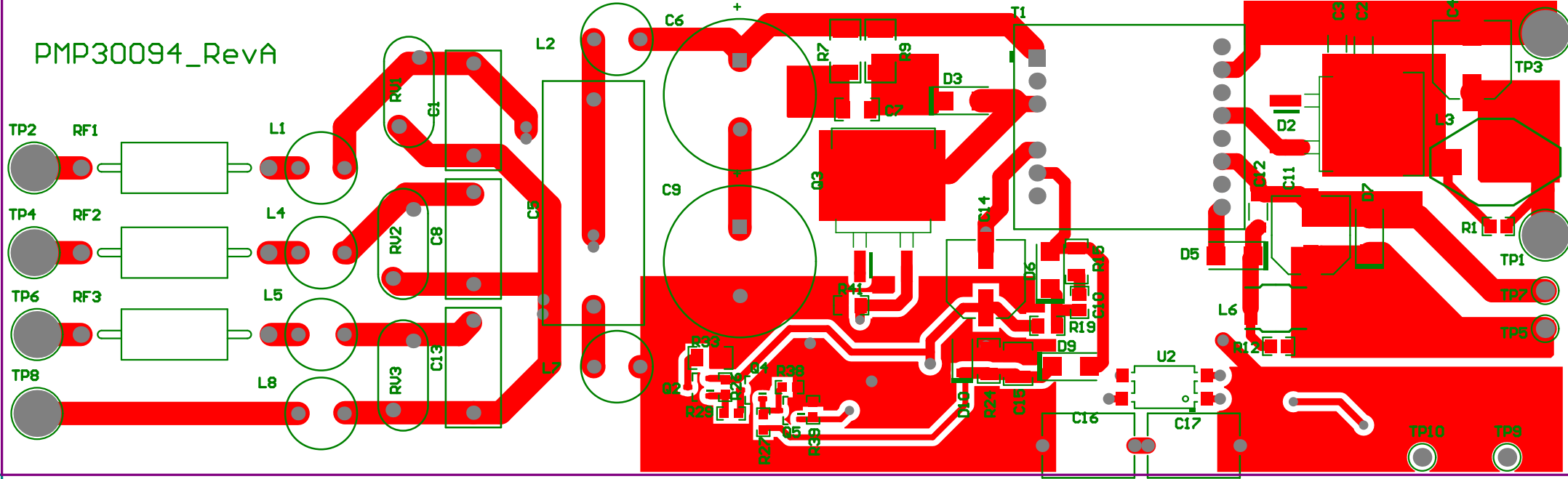


PMP30094_RevA



51.75mm

170.81mm



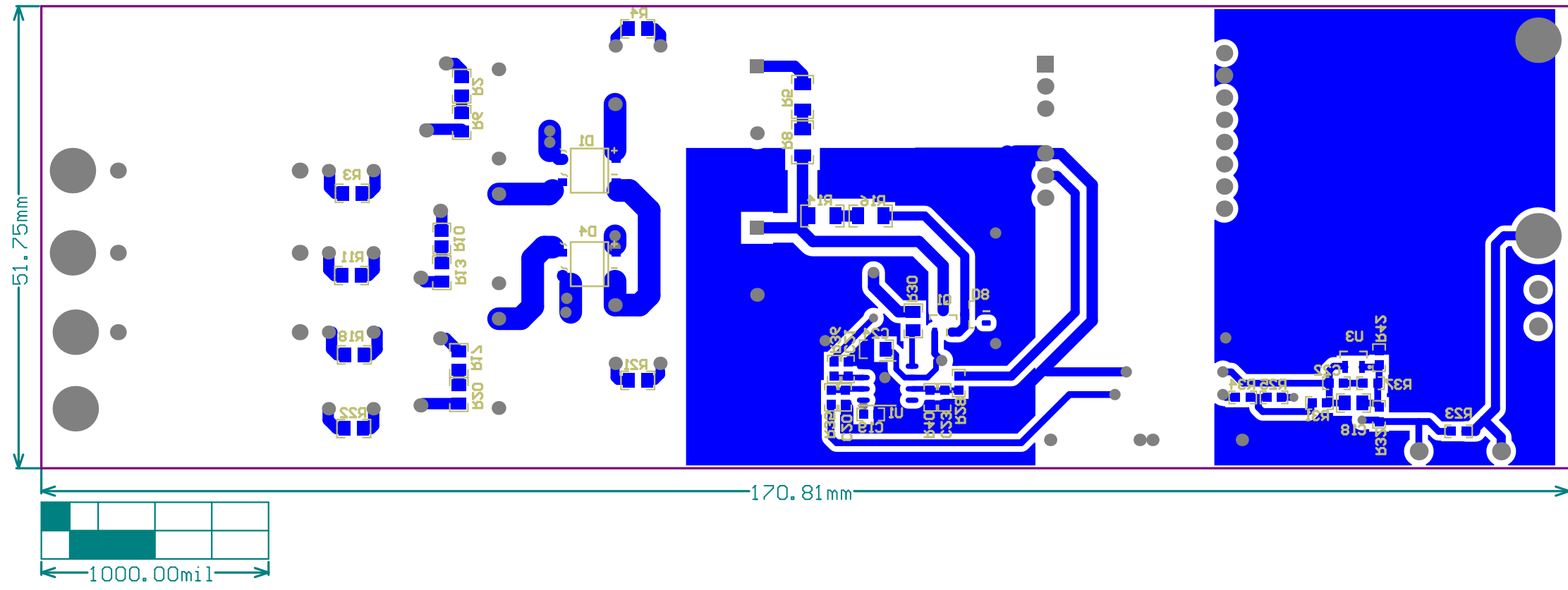
Top Board Dimensions



M1 Board Outline



M1 Board Outline



PCB Board Dimensions

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